

Title (en)  
HETEROGENEOUS NESTED INTERPOSER PACKAGE FOR IC CHIPS

Title (de)  
HETEROGENE VERSCHACHTELTE INTERPOSER-PACKUNG FÜR IC-CHIPS

Title (fr)  
BOÎTIER D'INTERPOSEUR EMBOÎTÉ HÉTÉROGÈNE POUR PUCES DE CI

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Application  
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Abstract (en)  
Embodiments disclosed herein include electronic packages and methods of fabricating electronic packages. In an embodiment, an electronic package comprises an interposer, where a cavity passes through the interposer, and a nested component in the cavity. In an embodiment, the electronic package further comprises a die coupled to the interposer by a first interconnect and coupled to the nested component by a second interconnect. In an embodiment, the first and second interconnects comprise a first bump, a bump pad over the first bump, and a second bump over the bump pad.

IPC 8 full level  
**H01L 21/683** (2006.01)

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**H01L 21/4853** (2013.01 - US); **H01L 21/4857** (2013.01 - US); **H01L 21/486** (2013.01 - US); **H01L 21/565** (2013.01 - US); **H01L 21/568** (2013.01 - US); **H01L 21/6835** (2013.01 - EP); **H01L 23/13** (2013.01 - KR); **H01L 23/29** (2013.01 - KR); **H01L 23/3128** (2013.01 - US); **H01L 23/3185** (2013.01 - KR); **H01L 23/49816** (2013.01 - KR); **H01L 23/538** (2013.01 - CN); **H01L 23/5381** (2013.01 - US); **H01L 23/5384** (2013.01 - KR US); **H01L 23/5385** (2013.01 - EP KR US); **H01L 23/5386** (2013.01 - CN KR US); **H01L 23/5389** (2013.01 - EP KR); **H01L 23/562** (2013.01 - US); **H01L 24/16** (2013.01 - US); **H01L 24/17** (2013.01 - EP); **H01L 24/96** (2013.01 - EP); **H01L 25/0655** (2013.01 - CN EP KR); **H01L 25/18** (2013.01 - CN); **H01L 25/50** (2013.01 - CN EP KR); **H01L 23/13** (2013.01 - EP); **H01L 23/3128** (2013.01 - EP); **H01L 23/49816** (2013.01 - EP); **H01L 24/03** (2013.01 - EP); **H01L 24/05** (2013.01 - EP); **H01L 24/13** (2013.01 - EP); **H01L 24/14** (2013.01 - EP); **H01L 24/16** (2013.01 - EP); **H01L 24/81** (2013.01 - EP); **H01L 24/97** (2013.01 - EP); **H01L 2221/68345** (2013.01 - EP); **H01L 2224/03003** (2013.01 - EP); **H01L 2224/031** (2013.01 - EP); **H01L 2224/03334** (2013.01 - EP); **H01L 2224/0401** (2013.01 - EP); **H01L 2224/04105** (2013.01 - EP); **H01L 2224/05568** (2013.01 - EP); **H01L 2224/0557** (2013.01 - EP); **H01L 2224/05647** (2013.01 - EP); **H01L 2224/06181** (2013.01 - EP); **H01L 2224/13025** (2013.01 - EP); **H01L 2224/131** (2013.01 - EP); **H01L 2224/1403** (2013.01 - EP); **H01L 2224/16145** (2013.01 - EP); **H01L 2224/16227** (2013.01 - EP US); **H01L 2224/16265** (2013.01 - EP); **H01L 2224/16267** (2013.01 - EP); **H01L 2224/17181** (2013.01 - EP); **H01L 2224/18** (2013.01 - EP); **H01L 2224/81005** (2013.01 - EP); **H01L 2224/81191** (2013.01 - EP); **H01L 2224/96** (2013.01 - EP); **H01L 2224/97** (2013.01 - EP); **H01L 2924/18161** (2013.01 - EP); **H01L 2924/3511** (2013.01 - KR US)

C-Set (source: EP)

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3. **H01L 2224/131 + H01L 2924/014 + H01L 2924/00014**

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